

DWG. NO. SD-53398-034

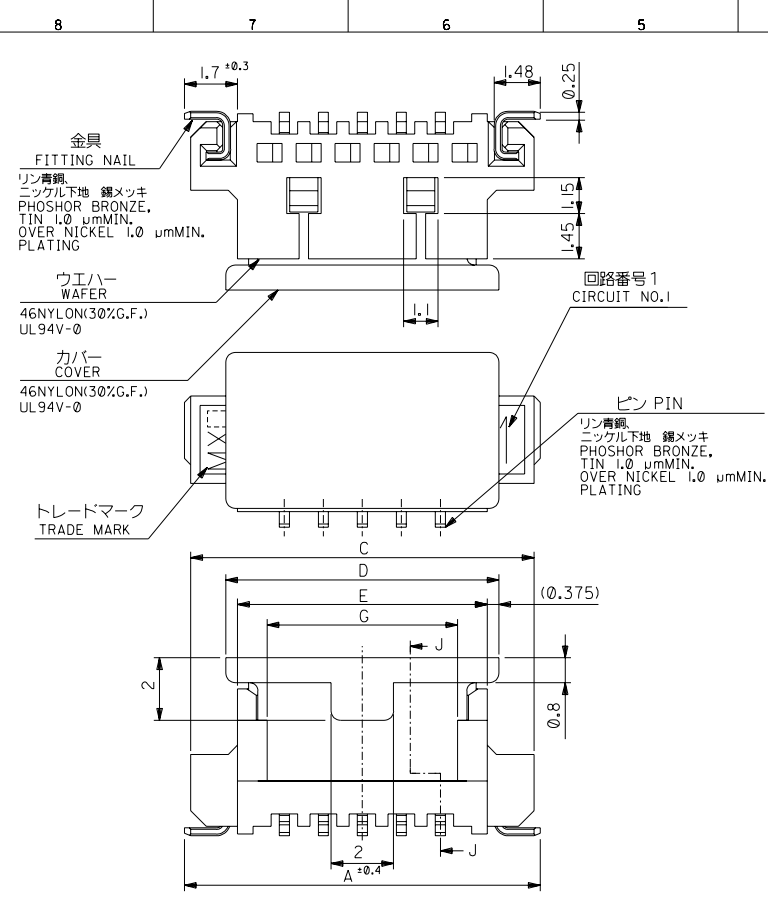
F

D

C

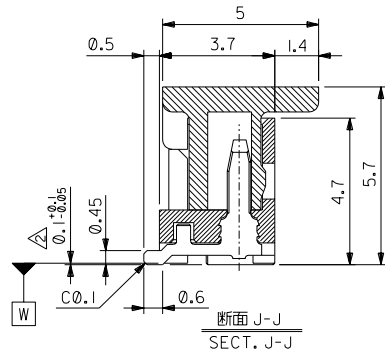
B

DO NOT SCALE DRAWING



NOTES

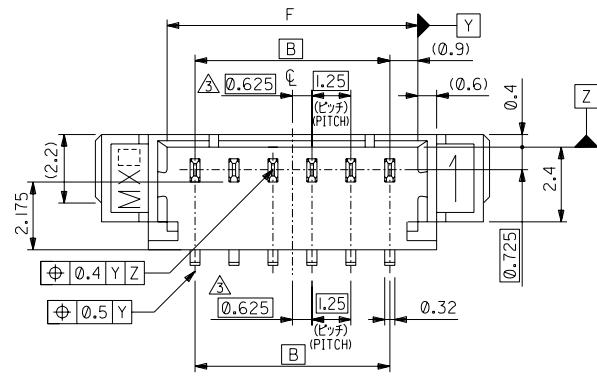
1. 嵌合相手: 51021シリーズ MATE WITH : 51021 SERIES
2. 水平面上においての、ウエハー底面 [W] とソルダーテール及びフィッティングネイル底面とのズレ量を示す。 MISALIGNMENT OF SOLDER TAIL & FITTING NAIL FROM [W]
3. 偶数極にのみ適用。 APPLY EVEN CIRCUIT PRODUCTS.
4. 本製品は 53398-**20 の鉛フリー品である。 THIS PRODUCT IS LEAD FREE OF 53398-**20.



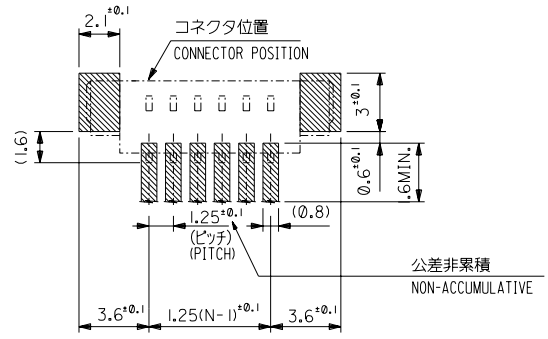
17.35	18.05	19.25	20	22.25	16.25	22.3	53398-1429	14
14.85	15.55	16.75	17.5	19.75	13.75	20.15	53398-1229	12
9.85	10.55	11.75	12.5	14.75	8.75	15.15	53398-0829	8
8.6	9.3	10.5	11.25	13.5	7.5	13.9	53398-0729	7
7.35	8.05	9.25	10	12.25	6.25	12.65	53398-0629	6
6.1	6.8	8	8.75	11	5	11.4	53398-0529	5
4.85	5.55	6.75	7.5	9.75	3.75	10.15	53398-0429	4
3.6	4.3	5.5	6.25	8.5	2.5	8.9	53398-0329	3
2.35	3.05	4.25	5	7.25	1.25	7.65	53398-0229	2
G	F	E	D	C	B	A	MATERIAL NO.	CIRCUITS

EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	RELEASED '04/02/12 EC NO. J2004-2404 DRWN: Y.SAKIYAMA CHK: M.SASAO APPR: M.SASAO	MATERIAL 材料 SEE DRAWING	GENERAL TOLERANCES: (UNLESS SPECIFIED) — 一般公差	SCALE —	MODEL NO. DESIGN UNITS 53398-**29 <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH	DIMENSIONS: THIRD ANGLE PROJECTION <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH <input type="checkbox"/> mm ONLY	SHT REV	
						FINISH 仕上げ	10 UNDER 未満		DRAWN BY & DATE Y.SAKIYAMA '04/02/12	TITLE: 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT (ST.) WITH COVER -LEAD FREE-	MATERIAL NO. SEE CHART	
						10 OVER 以上	30 UNDER 未満	CHECKED BY & DATE M.SASAO '04/02/12	APPROVED BY & DATE M.SASAO '04/02/12			DRAWING NO. SD-53398-034
						30 OVER 以上						
						WIRE RANGE 適用電線範囲	ANGLE 角度		CAD FILENAME SD-53398-034.S01		SIZE B	
						INS. RANGE 被覆外径			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.		EN-02J(097) MXJ-54	

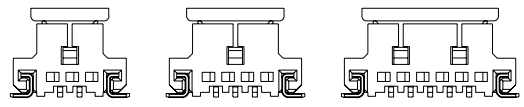
8 7 6 5 4 3 2 1



カバーなしの場合 (53398-**-19)
IN CASE OF WITHOUT COVER



参考基板レイアウト
RECOMMENDED P.C.BOARD PATTERN DIM.(REF.)



2種 2 CKT.
3種 3 CKT.
4種以上 OVER 4 CKT.

ロック形状図
LOCK CONFIGURATION

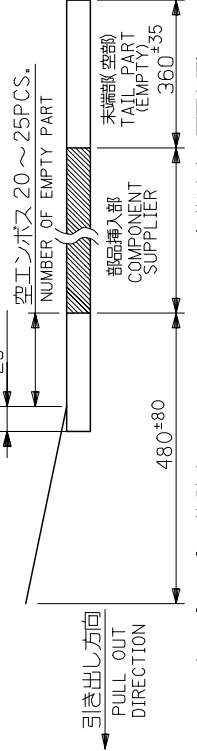
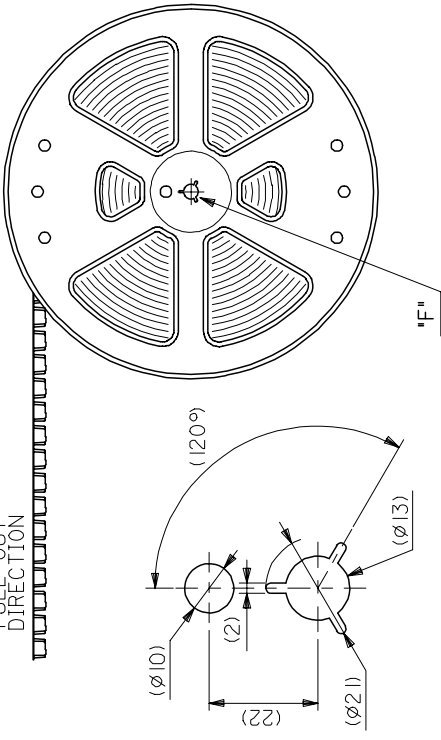
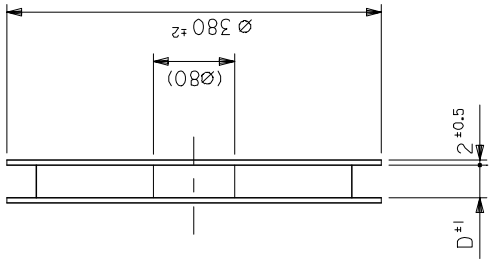
NOTES

△ ロック窓は、2、3種は1ヶ所、4種以上は2ヶ所とする。
LOCKING WINDOW : ONE PLACE FOR 2&3 CKTS.
TWO PLACES FOR MORE THAN 4 CKTS.

EC NO. DRWN: CHK'g: APPR:	EC NO. DRWN: CHK'g: APPR:	EC NO. DRWN: CHK'g: APPR:	EC NO. DRWN: CHK'g: APPR:	RELEASED '04/02/12	MATERIAL 材料 SEE NOTES	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	SCALE	MODEL NO.	53398-**-29	DIMENSIONS:	SHT	REV
							DESIGN UNITS	<input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH	THIRD ANGLE PROJECTION	<input type="checkbox"/> mm <input type="checkbox"/> INCH	<input type="checkbox"/> mm ONLY	REVISE ON CAD ONLY
							DRAWN BY & DATE	Y.SAKIYAMA '04/02/12	TITLE:	1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT (ST.) WITH COVER -LEAD FREE-		
							CHECKED BY & DATE	M.SASAO '04/02/12	APPROVED BY & DATE	M.SASAO '04/02/12	MOLEX	MATERIAL NO.
				INS. RANGE 被覆外径		ANGLE 角度	±3°	SD-53398-034.S02	SEE CHART	SD-53398-034	2 OF 2	SIZE B

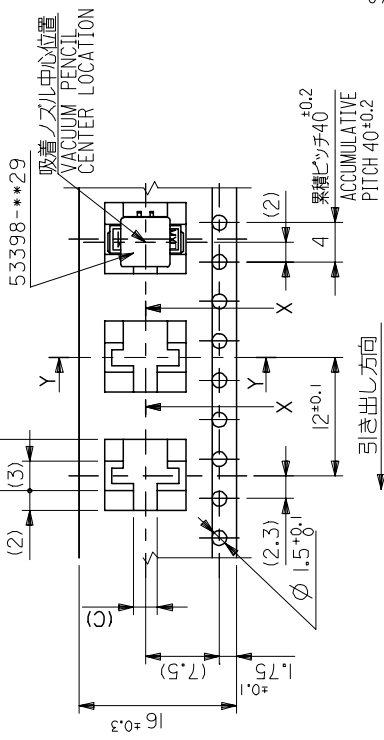
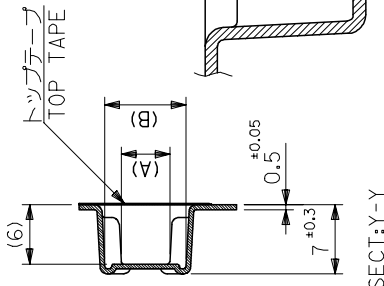
10 9 8 7 6 5 4 3 2 1

- NOTES
- 梱包数量: 1000個/リール
NUMBER OF CONNECTOR: 1000PCS/REEL
 - リードテープ長さ
LEAD TAPE LENGTH
25 \pm 10
 - トップテープ未接合部
TOP TAPE NON-BONDED PART



- トップテープの剥離強度: 0.6 \pm 0.35N(60 \pm 35gf) (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE: 0.6 \pm 0.35N(60 \pm 35gf)
(PEELING DIRECTION IS SHOWN IN FOLLOWING FIG.)
<剥離速度: 300mm/min(参考)>
PEELING SPEED: 300mm/min (REFERENCE)
- 剥離方向
PEEL OFF DIRECTION
10°
- 引き出し方向
PULL OUT DIRECTION
- 53398-**-29の詳細寸法については図面 SD-53398-034 を参照下さい。
RE DETAILED DIMENSIONS, SEE SD-53398-034.

- 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)
トップテープ (TOP TAPE): PET, PE, PEF
リール (REEL): ポリスチレン (PS) <リサイクル材含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- 本製品は 53398-**-80 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53398-**-80.



SECT: X-X

SECT: Y-Y

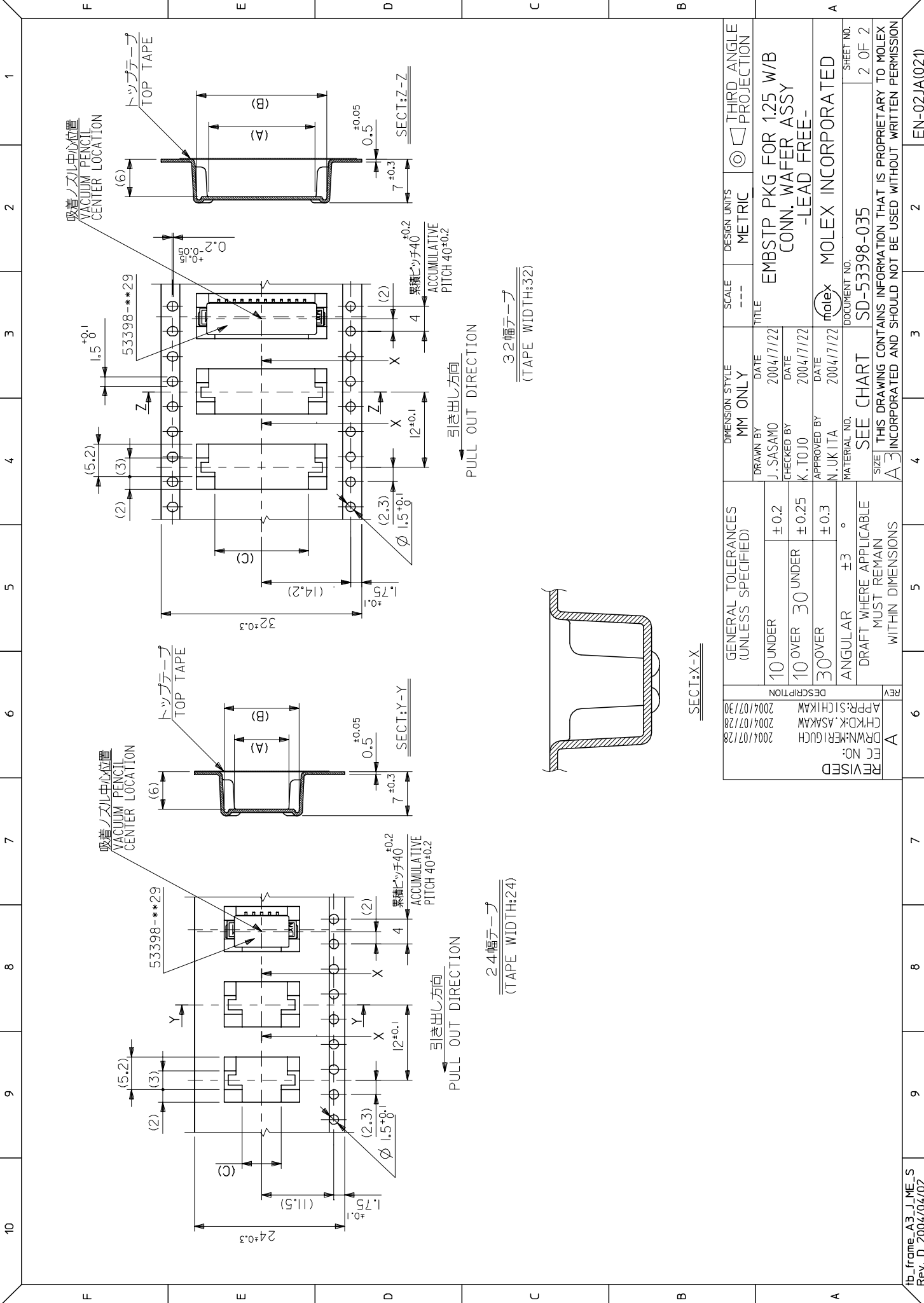
16幅テープ
(TAPE WIDTH: 16)

32	33.4	14.95	20.75	17.05	53398-1267	12
		9.95	15.75	12.05	53398-0867 <td>8</td>	8
		8.7	14.5	10.8	53398-0767 <td>7</td>	7
24	25.4	7.45	13.25	9.55	53398-0667 <td>6</td>	6
		6.2	12	8.3	53398-0567 <td>5</td>	5
		4.95	10.75	7.05	53398-0467 <td>4</td>	4
		3.7	9.5	5.8	53398-0367 <td>3</td>	3
16	17.4	2.45	8.25	4.55	53398-0267 <td>2</td>	2

DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
MM ONLY	---	---	---	---
DRAWN BY: J. SASAKI DATE: 2004/11/22				
CHECKED BY: K. TOJO DATE: 2004/11/22				
APPROVED BY: N. UKITA DATE: 2004/11/22				
MATERIAL NO. DOCUMENT NO. SD-53398-035				
TITLE: EMBSTP PKG FOR 1.25 W/B CONN. WAFER ASSY -LEAD FREE-				
SHEET NO. 1 OF 2				

GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	± 0.2
10 OVER	± 0.25
30 OVER	± 0.3
ANGULAR	$\pm 3^\circ$
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

REV	DESCRIPTION
A	REVISED
	EC NO. 2004/07/28
	DRW: MERRI GUCH
	CHK: K. ASAKAWA
	APP: S. ICHIKAWA
	2004/07/28

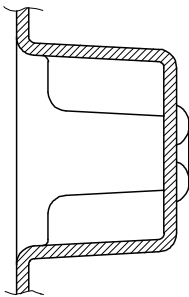


引き出し方向
PULL OUT DIRECTION

32幅テープ
(TAPE WIDTH:32)

引き出し方向
PULL OUT DIRECTION

24幅テープ
(TAPE WIDTH:24)



SECT: X-X

GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
10 UNDER ±0.2	10 OVER ±0.25	DRAWN BY J. SASAMO	DATE 2004/7/22	TITLE EMBSTP PKG FOR 1.25 W/B CONN. WAFER ASSY -LEAD FREE-	
30 OVER ±0.3	ANGULAR ±3 °	CHECKED BY K. TOJO	DATE 2004/7/22	DOCUMENT NO. MOLEX INCORPORATED	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY N. UKITA	DATE 2004/7/22	SHEET NO. 2 OF 2	
REVISED		SEE CHART		SIZE THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX A3 INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
DESCRIPTION	REV				
APPROVALS					
CHKD: K. ASAKAWA	2004/07/28				
DRWN: MERI GUCHI	2004/07/28				
EC NO:					